Lattice Semiconductor Corporation - LCMXO640E-3BN256C Datasheet

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Details	
Product Status	Active
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	159
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LFBGA, CSPBGA
Supplier Device Package	256-CABGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640e-3bn256c

MachXO Family Data Sheet Architecture

June 2013 Data Sheet DS1002

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

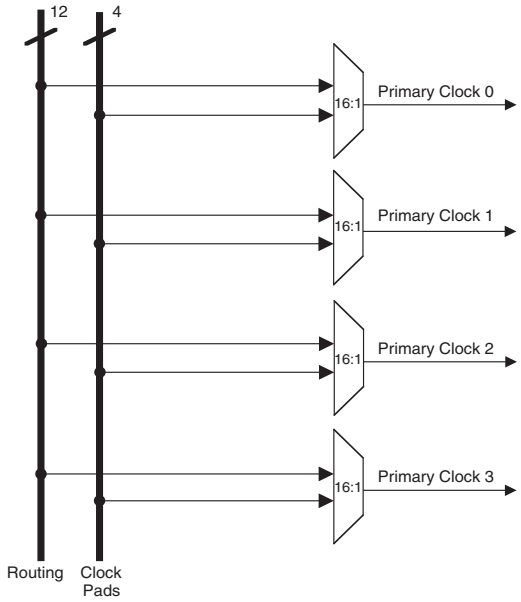
Note: SPR = Single Port RAM, DPR = Dual Port RAM

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock/Control Distribution Network

The MachXO family of devices provides global signals that are available to all PFUs. These signals consist of four primary clocks and four secondary clocks. Primary clock signals are generated from four 16:1 muxes as shown in Figure 2-7 and Figure 2-8. The available clock sources for the MachXO256 and MachXO640 devices are four dual function clock pins and 12 internal routing signals. The available clock sources for the MachXO1200 and MachXO2280 devices are four dual function clock pins, up to nine internal routing signals and up to six PLL outputs.

Figure 2-7. Primary Clocks for MachXO256 and MachXO640 Devices



sysCLOCK Phase Locked Loops (PLLs)

The MachXO1200 and MachXO2280 provide PLL support. The source of the PLL input divider can come from an external pin or from internal routing. There are four sources of feedback signals to the feedback divider: from CLKINTFB (internal feedback port), from the global clock nets, from the output of the post scalar divider, and from the routing (or from an external pin). There is a PLL_LOCK signal to indicate that the PLL has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider, and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-10. PLL Diagram

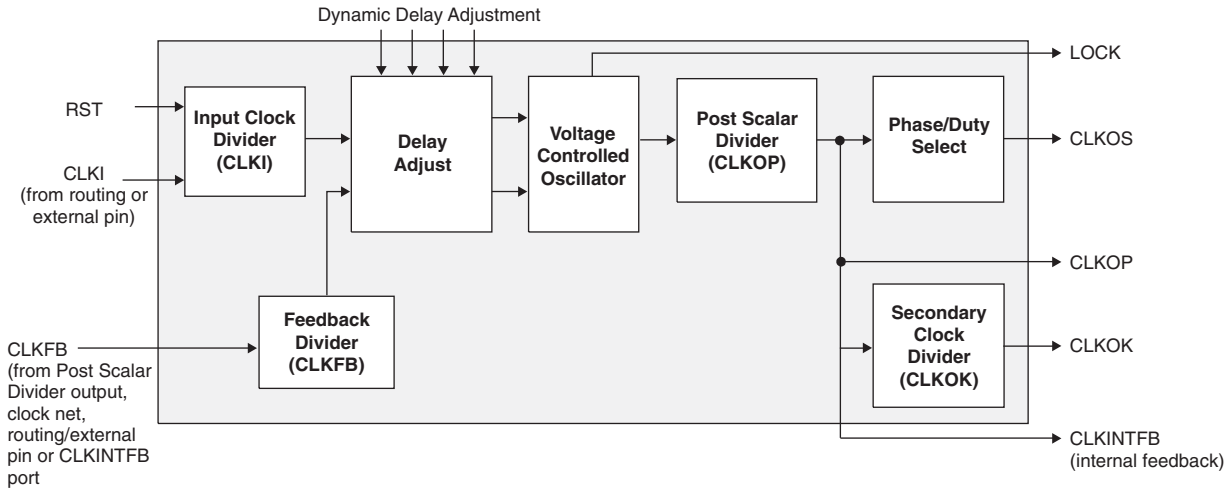
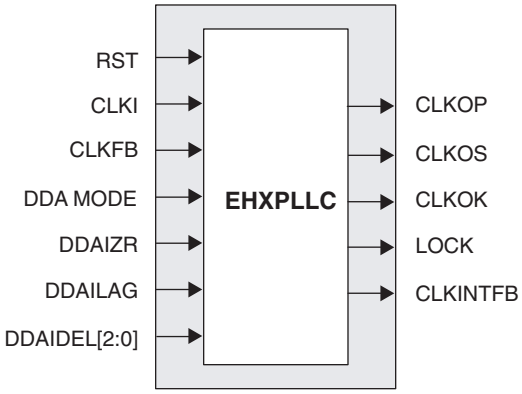


Figure 2-11 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive



the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO "C" devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <10mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1}; MachXO640: V_{CCIO2}; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Absolute Maximum Ratings[1, 2, 3]

	LCMXO E (1.2V)	LCMXO C (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied [4]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied[4]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[1]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[3]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[2]	I/O Driver Supply Voltage	1.14	3.465	V
t_{JCOM}	Junction Temperature Commercial Operation	0	+85	°C
t_{JIND}	Junction Temperature Industrial Operation	-40	100	°C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	+85	°C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	-40	100	°C

1. Like power supplies must be tied together. For example, if V_{CCIO} and V_{CC} are both 2.5V, they must also be the same supply. 3.3V V_{CCIO} and 1.2V V_{CCIO} should be tied to V_{CCAUX} or 1.2V V_{CC} respectively.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CC} must reach minimum V_{CC} value before V_{CCAUX} reaches 2.5V.

MachXO Programming/Erase Specifications

Symbol	Parameter	Min.	Max.	Units
$N_{PROGCYC}$	Flash Programming Cycles per $t_{RETENTION}$		1,000	Cycles
	Flash Functional Programming Cycles		10,000	Cycles
$t_{RETENTION}$	Data Retention at 125° Junction Temperature	10		Years

Supply Current (Sleep Mode)[1, 2]

Symbol	Parameter	Device	Typ.[3]	Max.	Units
I_{CC}	Core Power Supply	LCMXO256C	12	25	µA
		LCMXO640C	12	25	µA
		LCMXO1200C	12	25	µA
		LCMXO2280C	12	25	µA
I_{CCAUX}	Auxiliary Power Supply	LCMXO256C	1	15	µA
		LCMXO640C	1	25	µA
		LCMXO1200C	1	45	µA
		LCMXO2280C	1	85	µA
I_{CCIO}	Bank Power Supply[4]	All LCMXO 'C' Devices	2	30	µA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency = 0MHz.
3. T_A = 25°C, power supplies at nominal voltage.
4. Per Bank.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	7	mA
		LCMXO640C	9	mA
		LCMXO1200C	14	mA
		LCMXO2280C	20	mA
		LCMXO256E	4	mA
		LCMXO640E	6	mA
		LCMXO1200E	10	mA
		LCMXO2280E	12	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256E/C	5	mA
		LCMXO640E/C	7	mA
		LCMXO1200E/C	12	mA
		LCMXO2280E/C	13	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.
3. Frequency = 0MHz.
4. User pattern = blank.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

sysIO Differential Electrical Characteristics

LVDS

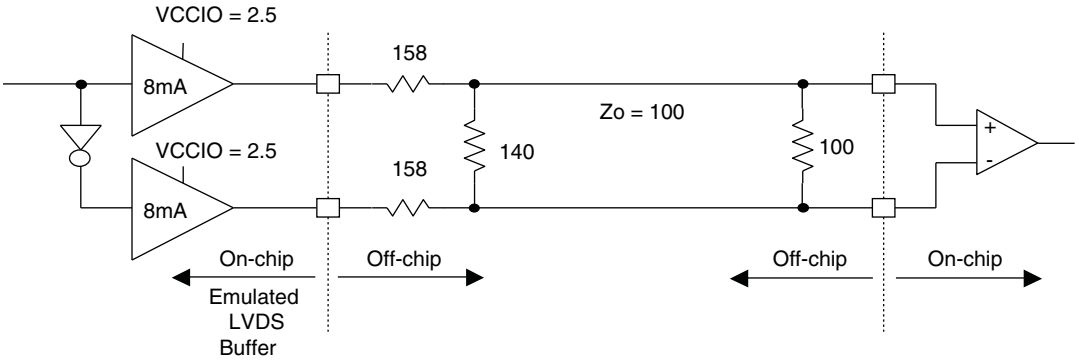
Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV ≤ V_{THD}	V_{THD}/2	1.2	1.8	V
		200mV ≤ V_{THD}	V_{THD}/2	1.2	1.9	V
		350mV ≤ V_{THD}	V_{THD}/2	1.2	2.0	V
I_{IN}	Input current	Power on	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 Ohm	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

LVDS Emulation

MachXO devices can support LVDS outputs via emulation (LVDS25E), in addition to the LVDS support that is available on-chip on certain devices. The output is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

Figure 3-1. LVDS Using External Resistors (LVDS25E)



Note: All resistors are ±1%.

The LVDS differential input buffers are available on certain devices in the MachXO family.

Table 3-1. LVDS DC Conditions

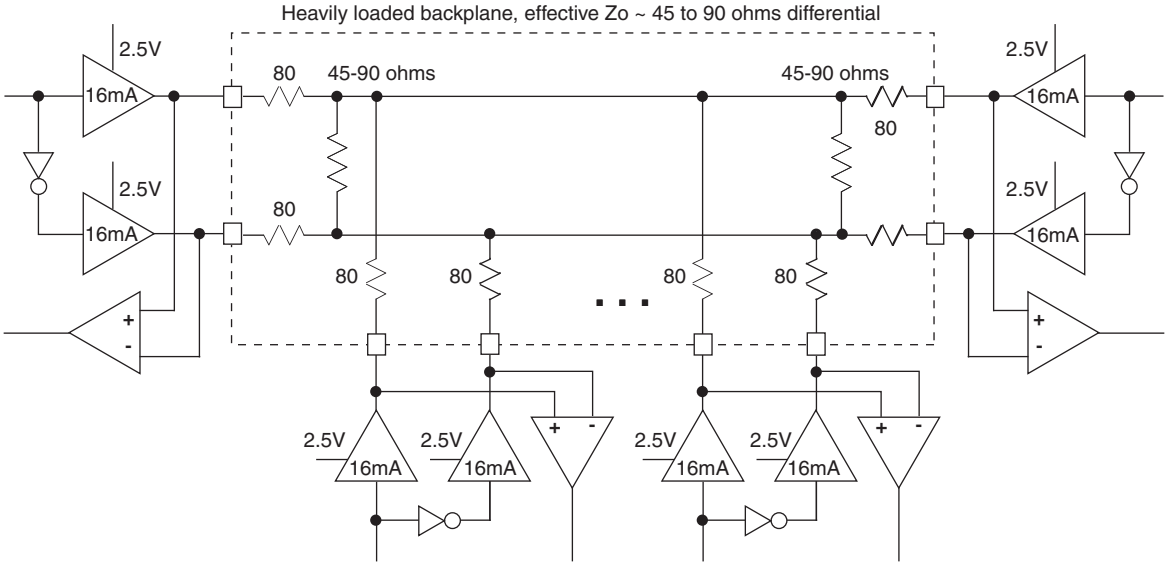
Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ω
R_S	Driver series resistor	294	Ω
R_P	Driver parallel resistor	121	Ω
R_T	Receiver termination	100	Ω
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	Ω
I_{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example



Typical Building Block Function Performance[1]

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

Register-to-Register Performance

Function	-5 Timing	Units
Basic Functions		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
Embedded Memory Functions (1200 and 2280 Devices Only)		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
Distributed Memory Functions		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

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Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

MachXO Internal Timing Parameters[1]

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t_{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t_{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t_{LSR_PFU}	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t_{SUM_PFU}	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t_{HM_PFU}	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t_{SUD_PFU}	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t_{HD_PFU}	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t_{CK2Q_PFU}	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t_{LE2Q_PFU}	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t_{LD2Q_PFU}	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
PFU Dual Port Memory Mode Timing								
t_{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t_{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t_{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t_{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t_{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t_{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t_{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
PIO Input/Output Buffer Timing								
t_{IN_PIO}	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t_{OUT_PIO}	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
EBR Timing (1200 and 2280 Devices Only)								
t_{CO_EBR}	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t_{COO_EBR}	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t_{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t_{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t_{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t_{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t_{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t_{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
PLL Parameters (1200 and 2280 Devices Only)								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Rev. A 0.19

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
51	TDI	2	TDI		TDI	5	TDI		TDI	5	TDI	
52	VCC	-			VCC	-			VCC	-		
53	VCCAUX	-			VCCAUX	-			VCCAUX	-		
54	PB5A	2		T	PB6F	5			PB8F	5		
55	PB5B	2	PCLKT2_1***	C	PB7B	4	PCLK4_1***		PB10F	4	PCLK4_1***	
56	PB5D	2			PB7C	4		T	PB10C	4		T
57	PB6A	2		T	PB7D	4		C	PB10D	4		C
58	PB6B	2	PCLKT2_0***	C	PB7F	4	PCLK4_0***		PB10B	4	PCLK4_0***	
59	GND	-			GND	-			GND	-		
60	PB7C	2			PB9A	4		T	PB12A	4		T
61	PB7E	2			PB9B	4		C	PB12B	4		C
62	PB8A	2			PB9E	4			PB12E	4		
63	VCCIO2	2			VCCIO4	4			VCCIO4	4		
64	GNDIO2	2			GNDIO4	4			GNDIO4	4		
65	PB8C	2		T	PB10A	4		T	PB13A	4		T
66	PB8D	2		C	PB10B	4		C	PB13B	4		C
67	PB9A	2		T	PB10C	4		T	PB13C	4		T
68	PB9C	2		T	PB10D	4		C	PB13D	4		C
69	PB9B	2		C	PB10F	4			PB14D	4		
70**	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
71	PB9D	2		C	PB11C	4		T	PB16C	4		T
72	PB9F	2			PB11D	4		C	PB16D	4		C
73	PR11D	1		C	PR16B	3		C	PR20B	3		C
74	PR11B	1		C	PR16A	3		T	PR20A	3		T
75	PR11C	1		T	PR15B	3		C*	PR19B	3		C
76	PR10D	1		C	PR15A	3		T*	PR19A	3		T
77	PR11A	1		T	PR14D	3		C	PR17D	3		C
78	PR10B	1		C	PR14C	3		T	PR17C	3		T
79	PR10C	1		T	PR14B	3		C*	PR17B	3		C*
80	PR10A	1		T	PR14A	3		T*	PR17A	3		T*
81	PR9D	1			PR13D	3			PR16D	3		
82	VCCIO1	1			VCCIO3	3			VCCIO3	3		
83	GNDIO1	1			GNDIO3	3			GNDIO3	3		
84	PR9A	1			PR12B	3		C*	PR15B	3		C*
85	PR8C	1			PR12A	3		T*	PR15A	3		T*
86	PR8A	1			PR11B	3		C*	PR14B	3		C*
87	PR7D	1			PR11A	3		T*	PR14A	3		T*
88	GND	-			GND	-			GND	-		
89	PR7B	1		C	PR10B	3		C*	PR13B	3		C*
90	PR7A	1		T	PR10A	3		T*	PR13A	3		T*
91	PR6D	1		C	PR8B	2		C*	PR10B	2		C*
92	PR6C	1		T	PR8A	2		T*	PR10A	2		T*
93	VCC	-			VCC	-			VCC	-		
94	PR5D	1			PR6B	2		C*	PR8B	2		C*
95	PR5B	1			PR6A	2		T*	PR8A	2		T*
96	PR4D	1			PR5B	2		C*	PR7B	2		C*
97	PR4B	1		C	PR5A	2		T*	PR7A	2		T*
98	VCCIO1	1			VCCIO2	2			VCCIO2	2		
99	GNDIO1	1			GNDIO2	2			GNDIO2	2		
100	PR4A	1		T	PR4C	2			PR5C	2		

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		C	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2		C	PR4D	2		C
104	PR2D	1		C	PR3C	2		T	PR4C	2		T
105	PR3A	1		T	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2		C	PR3B	2		C*
108	PR2A	1		T	PR2A	2		T	PR3A	2		T*
109	PT9F	0		C	PT11D	1		C	PT16D	1		C
110	PT9D	0		C	PT11C	1		T	PT16C	1		T
111	PT9E	0		T	PT11B	1		C	PT16B	1		C
112	PT9B	0		C	PT11A	1		T	PT16A	1		T
113	PT9C	0		T	PT10F	1		C	PT15D	1		C
114	PT9A	0		T	PT10E	1		T	PT15C	1		T
115	PT8C	0			PT10D	1		C	PT14B	1		C
116	PT8B	0		C	PT10C	1		T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		T	PT9F	1		C	PT12F	1		C
120	PT7E	0			PT9E	1		T	PT12E	1		T
121	PT7C	0			PT9B	1		C	PT12D	1		C
122	PT7A	0			PT9A	1		T	PT12C	1		T
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1		C	PT9D	1		C
126	PT5C	0			PT7A	1		T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		C	PT7B	0		C
131	PT4B	0		C	PT5C	0		T	PT7A	0		T
132	PT4A	0		T	PT5B	0		C	PT6D	0		
133	PT3F	0			PT5A	0		T	PT6E	0		T
134	PT3D	0			PT4B	0			PT6F	0		C
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		C	PT3D	0		C	PT4B	0		T
138	PT2F	0		C	PT3C	0		T	PT4A	0		C
139	PT3A	0		T	PT3B	0		C	PT3B	0		C
140	PT2D	0		C	PT3A	0		T	PT3A	0		T
141	PT2E	0		T	PT2D	0		C	PT2D	0		C
142	PT2B	0		C	PT2C	0		T	PT2C	0		T
143	PT2C	0		T	PT2B	0		C	PT2B	0		C
144	PT2A	0		T	PT2A	0		T	PT2A	0		T

*Supports true LVDS outputs.
**NC for “E” devices.
***Primary clock inputs arer single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
-	-				VCCIO4	VCCIO4	4			VCCIO4	VCCIO4	4		
-	-				GND	GNDIO4	4			GND	GNDIO4	4		
M10	PB6A	2		T	M10	PB7E	4		T	M10	PB10A	4		T
R9	PB6C	2		T	R9	PB8A	4		T	R9	PB11C	4		T
R10	PB6D	2		C	R10	PB8B	4		C	R10	PB11D	4		C
T10	PB7C	2		T	T10	PB8C	4		T	T10	PB12A	4		T
T11	PB7D	2		C	T11	PB8D	4		C	T11	PB12B	4		C
N10	NC				N10	PB8E	4		T	N10	PB12C	4		T
N11	NC				N11	PB8F	4		C	N11	PB12D	4		C
VCCIO2	VCCIO2	2			VCCIO4	VCCIO4	4			VCCIO4	VCCIO4	4		
GND	GNDIO2	2			GND	GNDIO4	4			GND	GNDIO4	4		
R11	PB7E	2		T	R11	PB9A	4		T	R11	PB13A	4		T
R12	PB7F	2		C	R12	PB9B	4		C	R12	PB13B	4		C
P11	PB8A	2		T	P11	PB9C	4		T	P11	PB13C	4		T
P12	PB8B	2		C	P12	PB9D	4		C	P12	PB13D	4		C
T13	PB8C	2		T	T13	PB9E	4		T	T13	PB14A	4		T
T12	PB8D	2		C	T12	PB9F	4		C	T12	PB14B	4		C
R13	PB9A	2		T	R13	PB10A	4		T	R13	PB14C	4		T
R14	PB9B	2		C	R14	PB10B	4		C	R14	PB14D	4		C
GND	GND	-			GND	GND	-			GND	GND	-		
T14	PB9C	2		T	T14	PB10C	4		T	T14	PB15A	4		T
T15	PB9D	2		C	T15	PB10D	4		C	T15	PB15B	4		C
P13**	SLEEPN	-	SLEEPN		P13**	SLEEPN	-	SLEEPN		P13**	SLEEPN	-	SLEEPN	
P14	PB9F	2			P14	PB10F	4			P14	PB15D	4		
R15	NC				R15	PB11A	4		T	R15	PB16A	4		T
R16	NC				R16	PB11B	4		C	R16	PB16B	4		C
P15	NC				P15	PB11C	4		T	P15	PB16C	4		T
P16	NC				P16	PB11D	4		C	P16	PB16D	4		C
VCCIO2	VCCIO2	2			VCCIO4	VCCIO4	4			VCCIO4	VCCIO4	4		
GND	GNDIO2	2			GND	GNDIO4	4			GND	GNDIO4	4		
GND	GNDIO1	1			GND	GNDIO3	3			GND	GNDIO3	3		
VCCIO1	VCCIO1	1			VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
M11	NC				M11	PR16B	3		C	M11	PR20B	3		C
L11	NC				L11	PR16A	3		T	L11	PR20A	3		T
N12	NC				N12	PR15B	3		C*	N12	PR18B	3		C*
N13	NC				N13	PR15A	3		T*	N13	PR18A	3		T*
M13	NC				M13	PR14D	3		C	M13	PR17D	3		C
M12	NC				M12	PR14C	3		T	M12	PR17C	3		T
N14	PR11D	1		C	N14	PR14B	3		C*	N14	PR17B	3		C*
N15	PR11C	1		T	N15	PR14A	3		T*	N15	PR17A	3		T*
L13	PR11B	1		C	L13	PR13D	3		C	L13	PR16D	3		C
L12	PR11A	1		T	L12	PR13C	3		T	L12	PR16C	3		T
M14	PR10B	1		C	M14	PR13B	3		C*	M14	PR16B	3		C*
VCCIO1	VCCIO1	1			VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
GND	GNDIO1	1			GND	GNDIO3	3			GND	GNDIO3	3		
L14	PR10A	1		T	L14	PR13A	3		T*	L14	PR16A	3		T*
N16	PR10D	1		C	N16	PR12D	3		C	N16	PR15D	3		C
M16	PR10C	1		T	M16	PR12C	3		T	M16	PR15C	3		T
M15	PR9D	1		C	M15	PR12B	3		C*	M15	PR15B	3		C*
L15	PR9C	1		T	L15	PR12A	3		T*	L15	PR15A	3		T*
L16	PR9B	1		C	L16	PR11D	3		C	L16	PR14D	3		C
K16	PR9A	1		T	K16	PR11C	3		T	K16	PR14C	3		T
K13	PR8D	1		C	K13	PR11B	3		C*	K13	PR14B	3		C*

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
T2	PL20B	6		C
P6	TMS	5	TMS	
V1	PB2A	5		T
U2	PB2B	5		C
T3	PB2C	5		T
N7	TCK	5	TCK	
R4	PB2D	5		C
R5	PB3A	5		T
T4	PB3B	5		C
VCC	VCC	-		
R6	PB3C	5		T
P7	PB3D	5		C
U3	PB4A	5		T
T5	PB4B	5		C
V2	PB4C	5		T
N8	TDO	5	TDO	
V3	PB4D	5		C
T6	PB5A	5		T
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		
U4	PB5B	5		C
P8	PB5C	5		T
T7	PB5D	5		C
V4	TDI	5	TDI	
R8	PB6A	5		T
N9	PB6B	5		C
U5	PB6C	5		T
V5	PB6D	5		C
U6	PB7A	5		T
VCC	VCC	-		
V6	PB7B	5		C
P9	PB7C	5		T
T8	PB7D	5		C
U7	PB8A	5		T
V7	PB8B	5		C
M10	VCCAUX	-		
U8	PB8C	5		T
V8	PB8D	5		C
VCCIO5	VCCIO5	5		
GND	GNDIO5	5		
T9	PB8E	5		T
U9	PB8F	5		C
V9	PB9A	4		T

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
J13	PR10C	2		T
M18	PR10B	2		C*
L18	PR10A	2		T*
GND	GNDIO2	2		
VCCIO2	VCCIO2	2		
H16	PR9D	2		C
H14	PR9C	2		T
K18	PR9B	2		C*
J18	PR9A	2		T*
J17	PR8D	2		C
VCC	VCC	-		
H18	PR8C	2		T
H17	PR8B	2		C*
G17	PR8A	2		T*
H13	PR7D	2		C
H15	PR7C	2		T
G18	PR7B	2		C*
F18	PR7A	2		T*
G14	PR6D	2		C
G16	PR6C	2		T
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
E18	PR6B	2		C*
F17	PR6A	2		T*
G13	PR5D	2		C
G15	PR5C	2		T
E17	PR5B	2		C*
E16	PR5A	2		T*
GND	GND	-		
F15	PR4D	2		C
E15	PR4C	2		T
D17	PR4B	2		C*
D18	PR4A	2		T*
B18	PR3D	2		C
C18	PR3C	2		T
C16	PR3B	2		C*
D16	PR3A	2		T*
C17	PR2B	2		C
D15	PR2A	2		T
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
GND	GNDIO1	1		
VCCIO1	VCCIO1	1		

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
F16	GND	-		
H10	GND	-		
H11	GND	-		
H8	GND	-		
H9	GND	-		
J10	GND	-		
J11	GND	-		
J4	GND	-		
J8	GND	-		
J9	GND	-		
K10	GND	-		
K11	GND	-		
K17	GND	-		
K8	GND	-		
K9	GND	-		
L10	GND	-		
L11	GND	-		
L8	GND	-		
L9	GND	-		
N2	GND	-		
P14	GND	-		
P5	GND	-		
R7	GND	-		
F14	VCC	-		
G11	VCC	-		
G9	VCC	-		
H7	VCC	-		
L7	VCC	-		
M9	VCC	-		
H6	VCCIO7	7		
J7	VCCIO7	7		
M7	VCCIO6	6		
K7	VCCIO6	6		
M8	VCCIO5	5		
R9	VCCIO5	5		
M12	VCCIO4	4		
M11	VCCIO4	4		
L12	VCCIO3	3		
K12	VCCIO3	3		
J12	VCCIO2	2		
H12	VCCIO2	2		
G12	VCCIO1	1		
G10	VCCIO1	1		

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
G8	VCCIO0	0		
G7	VCCIO0	0		

* Supports true LVDS outputs.
** NC for “E” devices.
*** Primary clock inputs are single-ended.

MachXO Family Data Sheet Ordering Information

June 2013 Data Sheet DS1002

Part Number Description

LCMXO XXXX X – X XXXXXX X XX

Device Family
MachXO PLD

Logic Capacity
256 LUTs = 256
640 LUTs = 640
1200 LUTs = 1200
2280 LUTs = 2280

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked as described.

Speed
3 = Slowest
4
5 = Fastest

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
M100 = 100-ball csBGA
M132 = 132-ball csBGA
B256 = 256-ball caBGA
FT256 = 256-ball ftBGA
FT324 = 324-ball ftBGA

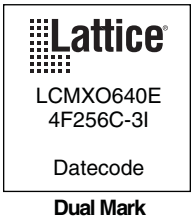
TN100 = 100-pin Lead-Free TQFP
TN144 = 144-pin Lead-Free TQFP
MN100 = 100-ball Lead-Free csBGA
MN132 = 132-ball Lead-Free csBGA
BN256 = 256-ball Lead-Free caBGA
FTN256 = 256-ball Lead-Free ftBGA
FTN324 = 324-ball Lead-Free ftBGA

Grade
C = Commercial
I = Industrial

ES = Engineering Sample
Blank = Production Device

Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device.þFor example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade.þThe slowest commercial speed grade does not have industrial markings.þ The markings appears as follows:



Dual Mark

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3TN100C	1200	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200E-4TN100C	1200	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200E-5TN100C	1200	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200E-3TN144C	1200	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200E-4TN144C	1200	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200E-5TN144C	1200	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200E-3MN132C	1200	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200E-4MN132C	1200	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200E-5MN132C	1200	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200E-3BN256C	1200	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200E-4BN256C	1200	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200E-5BN256C	1200	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200E-3FTN256C	1200	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200E-4FTN256C	1200	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200E-5FTN256C	1200	1.2V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3TN100C	2280	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO2280E-4TN100C	2280	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO2280E-5TN100C	2280	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO2280E-3TN144C	2280	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO2280E-4TN144C	2280	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO2280E-5TN144C	2280	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO2280E-3MN132C	2280	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO2280E-4MN132C	2280	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO2280E-5MN132C	2280	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO2280E-3BN256C	2280	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO2280E-4BN256C	2280	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO2280E-5BN256C	2280	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO2280E-3FTN256C	2280	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO2280E-4FTN256C	2280	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO2280E-5FTN256C	2280	1.2V	211	-5	Lead-Free ftBGA	256	COM
LCMXO2280E-3FTN324C	2280	1.2V	271	-3	Lead-Free ftBGA	324	COM
LCMXO2280E-4FTN324C	2280	1.2V	271	-4	Lead-Free ftBGA	324	COM
LCMXO2280E-5FTN324C	2280	1.2V	271	-5	Lead-Free ftBGA	324	COM